

## **STPS30H60-Y**

### Automotive power Schottky rectifier

Datasheet - production data

#### **Features**

- High junction temperature capability
- Avalanche rated
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- High frequency operation
- AEC-Q 101 qualified

#### **Description**

Dual centre tab Schottky rectifier suited for high frequency switch mode power supply.

Packaged in D<sup>2</sup>PAK, this device is designed for use in automotive applications. In these applications this device provides a good margin between the remaining voltage applied on the diode and the voltage capability of the diode.

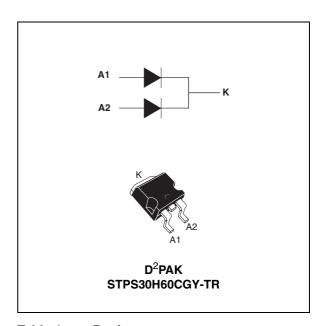


Table 1. Device summary

Symbol	Value
I <sub>F(AV)</sub>	2 X 15 A
V <sub>RRM</sub>	60 V
Tj	175 °C
V <sub>F (typ)</sub>	0.535 V

Characteristics STPS30H60-Y

#### 1 Characteristics

Table 2. Absolute ratings (limiting values per diode)

Symbol	Parameter	Value	Unit		
$V_{RRM}$	Repetitive peak reverse voltage				V
I <sub>F(RMS)</sub>	Forward rms current			30	Α
1	Average forward current, $\delta = 0.5$	T <sub>c</sub> = 155 °C	Per diode	15	А
I <sub>F(AV)</sub> Average	Average lorward current, 0 = 0.5		Total package	30	^
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinus	230	Α	
P <sub>ARM</sub>	Relative peak avalanche power	T <sub>j</sub> = 125 °C	t <sub>p</sub> = 10 μs	715	W
T <sub>j</sub>	Operating junction temperature range <sup>(1)</sup>			-40 to + 175	°C
T <sub>stg</sub>	Storage temperature range			-65 to + 175	°C

<sup>1.</sup>  $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit	
В	Junction to case	ode	1.5	
R <sub>th(j-c)</sub> Junction t	Total		0.8	°C/W
R <sub>th(c)</sub>	Coupling	0.1		

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
ı (1) D	Reverse leakage current	T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$			60	μΑ
'R`		T <sub>j</sub> = 125 °C			8	25	mA
	V <sub>F</sub> <sup>(2)</sup> Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 7.5 A			550	
		T <sub>j</sub> = 125 °C			435	470	
V (2)		T <sub>j</sub> = 25 °C				660	mV
<b>v</b> F` ′		T <sub>j</sub> = 125 °C			535	570	IIIV
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A			820	
		$T_j = 125  ^{\circ}\text{C}$	] IF = 30 A		635	690	

<sup>1.</sup> Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$ 

To evaluate the conduction losses use the following equation:

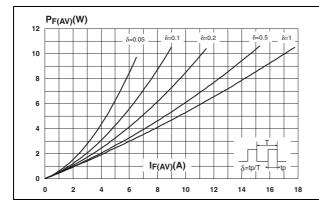
$$P = 0.45 \times I_{F(AV)} + 0.008 \times I_{F}^{2}_{(RMS)}$$

<sup>2.</sup> Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%

STPS30H60-Y Characteristics

Figure 1. Conduction losses versus average forward current

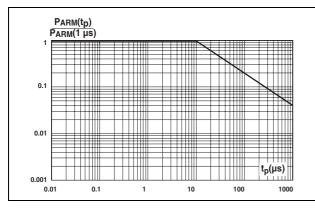
Figure 2. Average forward current versus ambient temperature  $(\delta = 0.5, \text{ per diode})$ 



18
16
16
14
12
10
8
R<sub>ncj-aj</sub>=15 °CW
6
4
2
0
0
25
50
75
100
125
150
175

Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Relative variation of thermal impedance junction to case versus pulse duration



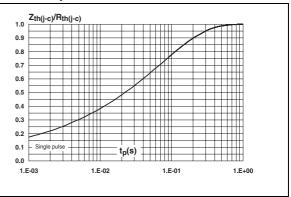
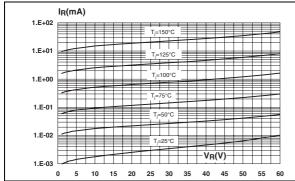
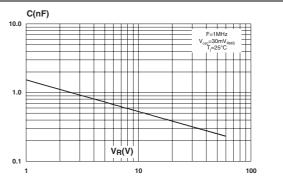


Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

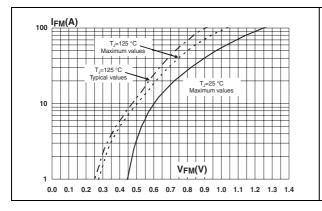


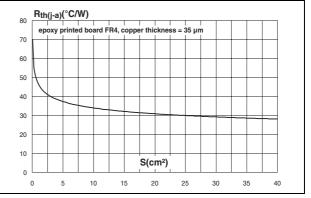


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Figure 7. Forward voltage drop versus forward current (per diode)

Figure 8. Thermal resistance junction to ambient versus copper surface under tab





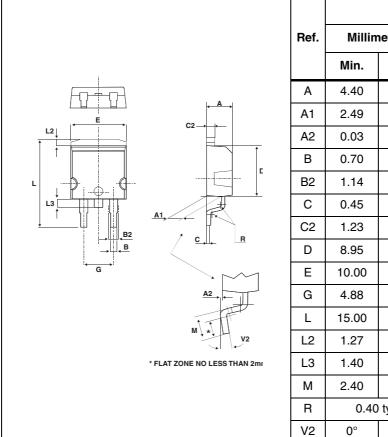
STPS30H60-Y Package information

## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

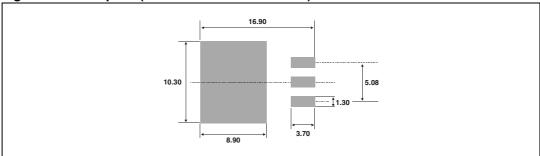
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 5. D<sup>2</sup>PAK dimensions



	Dimensions			
Ref.	Millimeters		Inc	hes
	Min.	Max	Min.	Max.
Α	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
В	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
С	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
Е	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
М	2.40	3.20	0.094	0.126
R	0.40 typ.		0.010	6 typ.
V2	0°	8°	0°	8°

Figure 9. Footprint (dimensions in millimeters)



Ordering information STPS30H60-Y

# **3** Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30H60CGY-TR	STPS30H60CGY-TR	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

# 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
20-Mar-2012	1	First issue.

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